

1.5V Drive Pch MOSFET

RP1A090ZP

Structure

Silicon P-channel MOSFET

Features

- 1) Low Voltage Drive(1.5V drive).
- 2) Built-in G-S Protection Diode.
- 3) Small Surface Mount Package (MPT6).

Application

Switching

Packaging specifications

Type	Package	Taping	
	Code	TR	
	Basic ordering unit (pieces)	1000	
RP1A090Z	0		

● Absolute maximum ratings (Ta = 25°C)

Paran	Symbol	Limits	Unit	
Drain-source voltage		V_{DSS}	-12	V
Gate-source voltage		V_{GSS}	±10	V
Drain current	Continuous	I _D	<u>+9</u>	Α
	Pulsed	I _{DP} *1	±36	Α
Source current (Body Diode)	Continuous	I _S	-1.6	Α
	Pulsed	I _{SP} *1	-36	Α
Power dissipation		P _D *2	2.0	W
Channel temperature		Tch 150		°C
Range of storage temperature		Tstg	-55 to +150	°C

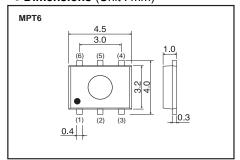
^{*1} Pw≤10µs, Duty cycle≤1%

• Thermal resistance

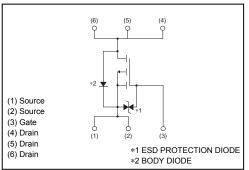
Parameter	Symbol	Limits	Unit
Channel to Ambient	Rth (ch-a)*	62.5	°C/W

^{*}Mounted on a ceramic board.

● Dimensions (Unit : mm)



• Inner circuit



^{*2} Mounted on a ceramic board.

● Electrical characteristics (Ta = 25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Gate-source leakage	I_{GSS}	1	-	±10	μA	V_{GS} =±10V, V_{DS} =0V
Drain-source breakdown voltage	$V_{(BR)DSS}$	-12	-	-	٧	I _D =-1mA, V _{GS} =0V
Zero gate voltage drain current	I _{DSS}	1	-	-1	μA	V _{DS} =-12V, V _{GS} =0V
Gate threshold voltage	V _{GS (th)}	-0.3	-	-1.0	٧	V_{DS} =-6V, I_{D} =-1mA
		1	8	12		I _D =-9A, V _{GS} =-4.5V
Static drain-source on-state	R*	1	11	16	m()	$I_D = -4.5A, V_{GS} = -2.5V$
resistance	R _{DS (on)}	-	15	23	mΩ	I _D =-4.5A, V _{GS} =-1.8V
		-	19	38		I _D =-1.8A, V _{GS} =-1.5V
Forward transfer admittance	IY _{fs} I*	12	-	-	S	I _D =-9A, V _{DS} =-6V
Input capacitance	C _{iss}	1	7400	-	pF	V _{DS} =-6V
Output capacitance	C _{oss}	1	800	-	pF	V _{GS} =0V
Reverse transfer capacitance	C _{rss}	1	750	-	pF	f=1MHz
Turn-on delay time	t _{d(on)} *	1	35	-	ns	I _D =-4.5A, V _{DD} ≒-6V
Rise time	t _r *	ı	120	-	ns	V _{GS} =-4.5V
Turn-off delay time	t _{d(off)} *	-	350	-	ns	R_L =1.3 Ω
Fall time	t _f *	-	170	-	ns	R_G =10 Ω
Total gate charge	Q _g *	-	59	_	nC	I _D =-9A,
Gate-source charge	Q _{gs} *	-	11	-	nC	V _{GS} =-4.5V
Gate-drain charge	Q _{gd} *	-	9	-	nC	V _{DD} ≒-6V

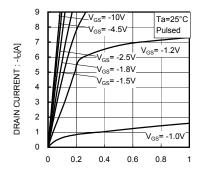
^{*}Pulsed

●Body diode characteristics (Source-Drain) (Ta = 25°C)

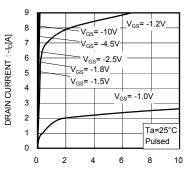
Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Forward Voltage	V _{SD} *	-	-	-1.2	V	I _s =-9A, V _{GS} =0V

^{*}Pulsed

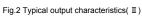
• Electrical characteristic curves

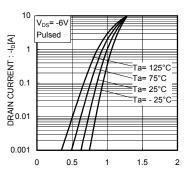


DRAIN-SOURCE VOLTAGE : $-V_{DS}[V]$ Fig.1 Typical output characteristics(I)



DRAIN-SOURCE VOLTAGE : -V_{DS}[V]





 $\mathsf{GATE}\text{-}\mathsf{SOURCE}\;\mathsf{VOLTAGE}: \text{-}\mathsf{V}_\mathsf{GS}[\mathsf{V}]$

Fig.3 Typical Transfer Characteristics

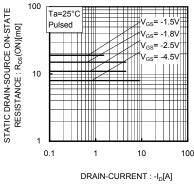


Fig.4 Static Drain-Source On-State Resistance vs. Drain Current(I)

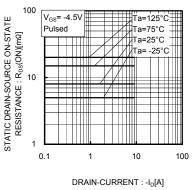


Fig.5 Static Drain-Source On-State Resistance vs. Drain Current(II)

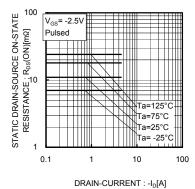


Fig.6 Static Drain-Source On-State
Resistance vs. Drain Current(Ⅲ)

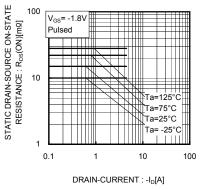


Fig.7 Static Drain-Source On-State
Resistance vs. Drain Current(IV)

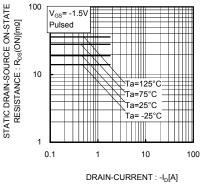


Fig.8 Static Drain-Source On-State
Resistance vs. Drain Current(V)

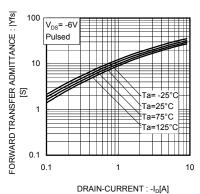
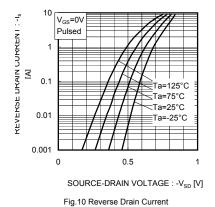
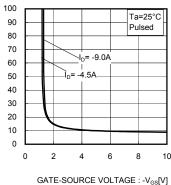


Fig.9 Forward Transfer Admittance vs. Drain Current



vs. Sourse-Drain Voltage

STATIC DRAIN-SOURCE ON-STATE RESISTANCE : $R_{DS}(ON)[m\Omega]$



10000 SWITCHING TIME: t [ns] 1000 100 10 $R_G = 10\Omega$ 0.01 0.1 10 100

Fig.11 Static Drain-Source On-State Resistance vs. Gate Source Voltage

DRAIN-CURRENT : -I_D[A] Fig.12 Switching Characteristics

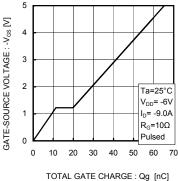


Fig.13 Dynamic Input Characteristics

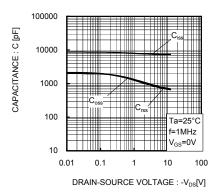
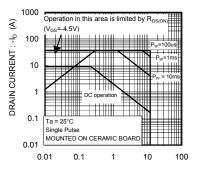


Fig.14 Typical Capacitance vs. Drain-Source Voltage



DRAIN-SOURCE VOLTAGE : $-V_{DS}[V]$

Fig.15 Maximum Safe Operating Aera

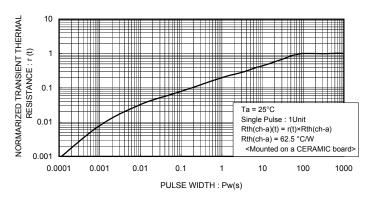


Fig.16 Normalized Transient Thermal Resistance vs. Pulse Width

Measurement circuits

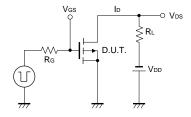


Fig.1-1 Switching Time Measurement Circuit

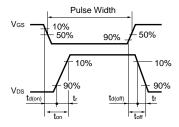


Fig.1-2 Switching Waveforms

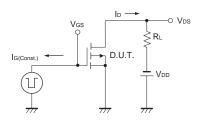


Fig.2-1 Gate charge measurement circuit

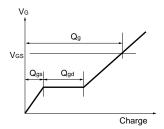


Fig.2-2 Gate Charge Waveform

Notice

This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.

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